

## AMENDMENTS TO THE CLAIMS

### **Claims 1-10 (Cancelled)**

**Claim 11 (Currently Amended)** A substrate processing apparatus comprising:

a polishing unit including a polishing tape, said polishing unit for polishing configured to polish a bevel portion of a substrate by bringing ~~a~~ said polishing tape into sliding contact with the bevel portion of the substrate;

a cleaning unit ~~for cleaning~~ configured to clean at least the bevel portion of the substrate;  
and

a drying unit ~~for drying~~ configured to dry the substrate which has been cleaned by said cleaning unit;

~~wherein said polishing unit has a polishing chamber therein, and an internal pressure of said polishing chamber is set to be lower than an external pressure of said polishing chamber.~~

a transfer robot configured to transfer the dried substrate to a wafer cassette;

a first partition dividing an internal space of said substrate processing apparatus into a transferring area in which said transfer robot is disposed and a cleaning area in which said cleaning unit and said drying unit are disposed; and

a second partition dividing the internal space of said substrate processing apparatus into said cleaning area and a polishing area in which said polishing unit is disposed,

wherein an internal pressure of said polishing area is set to be lower than an internal pressure of said cleaning area, and an internal pressure of said transferring area is set to be higher than the internal pressure of said cleaning area.

**Claim 12 (Original)** A substrate processing apparatus according to claim 11, wherein said polishing unit brings said polishing tape into sliding contact with the bevel portion and an edge portion of the substrate so as to polish the bevel portion and the edge portion.

**Claim 13 (Currently Amended)** A substrate processing apparatus according to claim 11, wherein said polishing unit brings ~~a~~ said polishing tape into sliding contact with a notch portion of the substrate so as to polish the notch portion.

**Claim 14 (Cancelled)**

**Claim 15 (Currently Amended)** A substrate processing apparatus according to claim ~~14~~ 11, further comprising a fan unit ~~for forming~~ configured to form a downward current of a clean gas in said cleaning area.

**Claim 16 (Currently Amended)** A substrate processing apparatus according to claim 11, further comprising a chemical mechanical polishing unit ~~for polishing~~ configured to polish a surface of the substrate by pressing the substrate against a polishing table, said chemical mechanical polishing unit being disposed in said polishing area.

**Claims 17-20 (Cancelled)**